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# Driving the Xilinx Analog-to-Digital Converter

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## Summary

Driving analog-to-digital converters (ADCs) is an extremely well documented subject, and there exists a vast amount of publicly available information on the topic. This application note provides the board designer with simple guidelines for common use cases of the Xilinx 7 series FPGAs analog-to-digital converter (XADC). Following the guidelines outlined in this application note will ensure optimum performance when driving the XADC. Layout guidelines for the XADC are described in *XADC Layout Guidelines* [Ref 1]. For information about the Analog Mixed Signal (AMS) capabilities of 7 series devices, go to [www.xilinx.com/ams](http://www.xilinx.com/ams).

## XADC

From the external printed circuit board (PCB), the XADC inputs can be viewed as a switched capacitor circuit similar to a traditional successive approximation register (SAR) ADC. [Figure 1](#) illustrates an equivalent circuit for both unipolar and bipolar modes of the XADC.

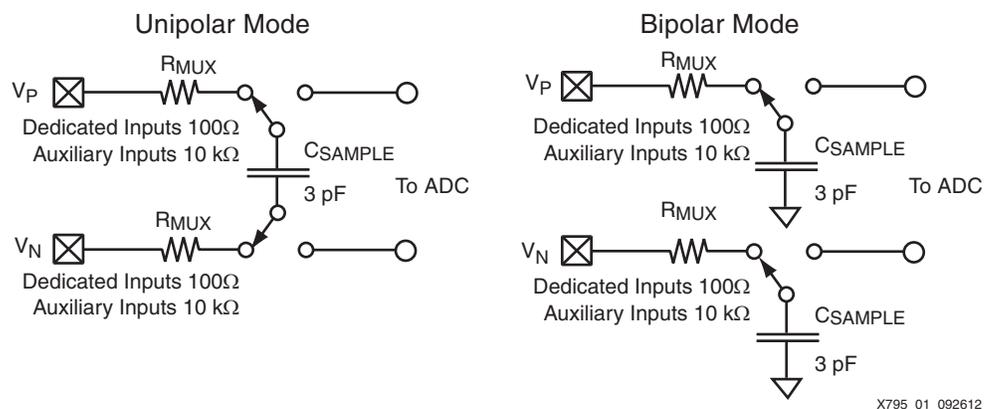
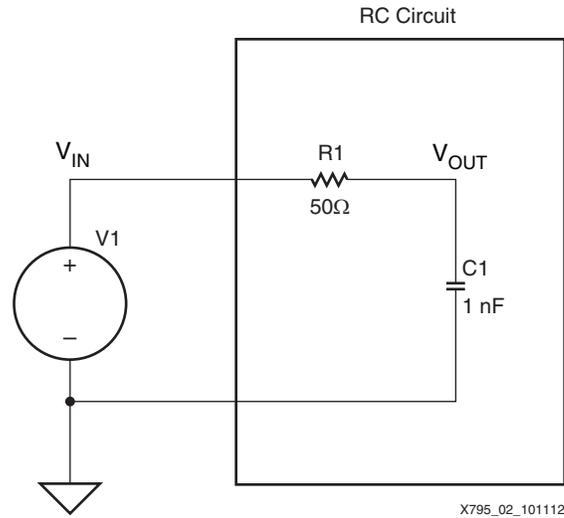


Figure 1: The XADC Input Equivalent Circuit During Acquisition

Similar to other ADCs, the XADC relies on the accuracy of the voltage across the capacitor,  $C_{SAMPLE}$ , for the accuracy of its conversion. A resistor and capacitor (RC) circuit as shown in [Figure 1](#) takes a finite amount of time to settle to final voltage. The required accuracy of the signal is defined by the desired level of system accuracy. Given that the XADC is 12 bits, the minimum likely settling error would be less than one half of the least significant bit (LSB) of a 12-bit value (13 bits of accuracy).

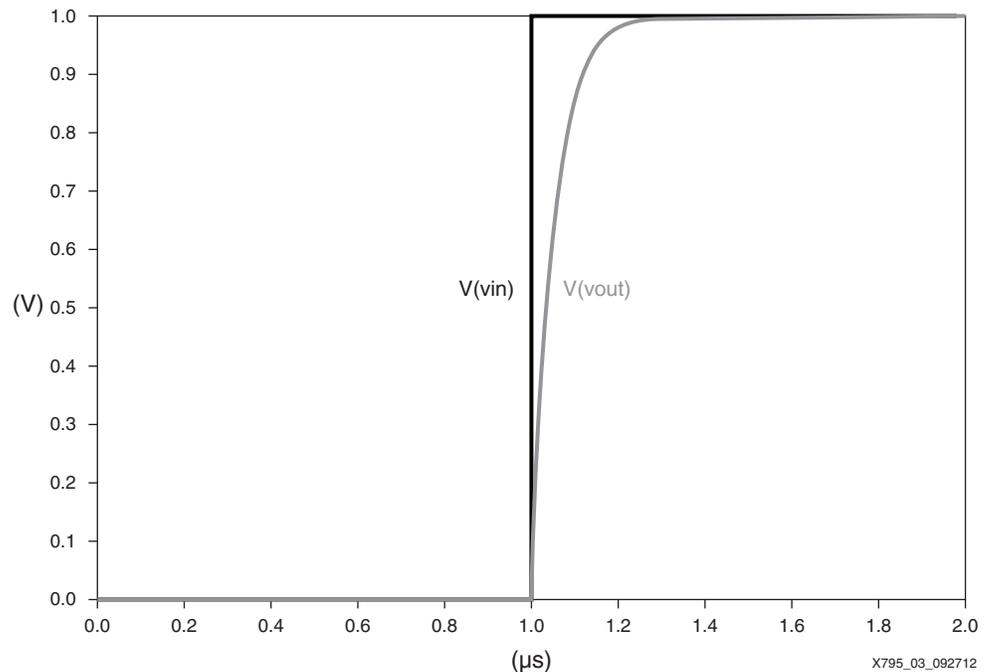
## Analysis of an RC Circuit

Before each use case of the XADC is analyzed, a simple RC circuit as shown in [Figure 2](#) is analyzed. This analysis forms the basis for subsequent detailed analysis of each individual use case.



**Figure 2: Simple RC Circuit with Ideal Source**

The response of the circuit shown in [Figure 2](#) can be simulated when a step input is applied. This simulation allows the calculation of the settling time for an RC circuit. [Figure 3](#) shows the output voltage ( $V_{OUT}$ ) of the RC circuit to a step voltage at its input ( $V_{IN}$ ) at  $t = 1 \mu\text{s}$ . The response of the circuit is exponential in nature. As time progresses, the desired output voltage is approached.



**Figure 3: Simulation Plot of the Step Response of an RC Circuit**

Assuming an initial voltage of zero across the capacitor, the circuit response is governed by [Equation 1](#).

$$V_{OUT}(t) = v_{in} \left( 1 - e^{-\frac{t}{RC}} \right) \quad \text{Equation 1}$$

[Equation 1](#) indicates that as time increases, the error associated with the settling of the circuit decreases proportionally to the RC product known as the time constant,  $\tau$ . The smaller the time constant, the faster the error term approaches an acceptable level.

Designers typically have an error budget measured in the number of bits or error percentage that must be achieved. Normally, the settling error would not be equal to the full error budget. Instead, one half of the total budget would be allowed for settling error. For an error budget of 12 bits or 0.025%, enough settling time for 13 bits or 0.0125% would be allowed. [Table 1](#) shows the time constant values required for a one half LSB error for each of the ADC resolutions.

**Table 1: Time Constant Values Required for Specific Resolutions**

Resolution (bits)	Error (%)	Number of Time Constants
6	0.3906	4.85
8	0.0977	6.24
10	0.0244	7.62
12	0.0061	9.01
14	0.0015	10.4

[Equation 2](#) shows how to calculate the settling time for an RC circuit for various levels of accuracy.

$$t_{settle} = (\text{Number of Time Constants}) \times RC \quad \text{Equation 2}$$

The first step to using [Equation 2](#) is to find the required number of time constants in [Table 1](#) to achieve the appropriate level of accuracy. For example, 12 bits of accuracy requires 9.01 time constants.

In the RC filter that makes up the equivalent circuit for the XADC input during the tracking phase in unipolar mode, the settling time required is given by [Equation 3](#).

$$t_{settle} = 9.01 \times 2 \times 10k\Omega \times 3pF = 540ns \quad \text{Equation 3}$$

Given that the total acquisition time of the XADC is 750 ns, there is no issue with settling the XADC input circuit in this instance. Settling time issues can arise due to the source impedance of the driving circuit (resistor divider application) or due to other poles in the system (other RC circuits or in the active source itself) at lower frequencies. These issues are discussed individually in subsequent sections of this application note.

## Issues Associated with Inadequate Settling Time

Failure to provide sufficient settling time means that the sampling capacitor cannot settle to its final accurate voltage resulting in a number of unwanted effects:

- ADC gain errors
- Temperature sensitivity to ADC gain error
- Crosstalk when using an external multiplexer

These issues occur with a majority of ADCs that use this type of switched capacitor input scheme. However, with some understanding and care, it is easy to avoid these issues when designing the analog input circuit for the XADC. Numerous tutorials and reference materials are available, such as *Designing SAR ADC Drive Circuitry, Part II* [[Ref 2](#)], *Designing SAR ADC Drive Circuitry, Part III* [[Ref 3](#)], *Analog-to-Digital Confusion: Pitfalls of Driving an ADC* [[Ref 4](#)], and *Switched-Capacitor ADC Analog Input Calculations* [[Ref 5](#)]. This application note addresses the specific requirements of the 7 series FPGAs XADC.

## Unique Benefits of XADC

The sampling period of an ADC is typically made up of two time periods: conversion time and acquisition time. During the acquisition time period, the ADC starts to acquire its next sample which is digitized in the conversion phase. In many ADCs, the acquisition time period can be as little as 10% of the overall conversion time. In some 1 MSPS ADCs, only 100 ns are available for the ADC to acquire its next sample. Consequently, whatever is driving the ADC needs to be capable of driving the capacitive load presented by the ADC and to settle within 100 ns. This requirement can be a significant challenge to meet.

The XADC addresses this issue by allowing the conversion and acquisition phases to occur in parallel resulting in greater than 75% of the overall sample time being available for acquisition, as shown in Figure 4. This arrangement significantly reduces the requirements for the analog front end driving the XADC, the benefit of which is illustrated in each of the use cases analyzed in subsequent sections of this application note.

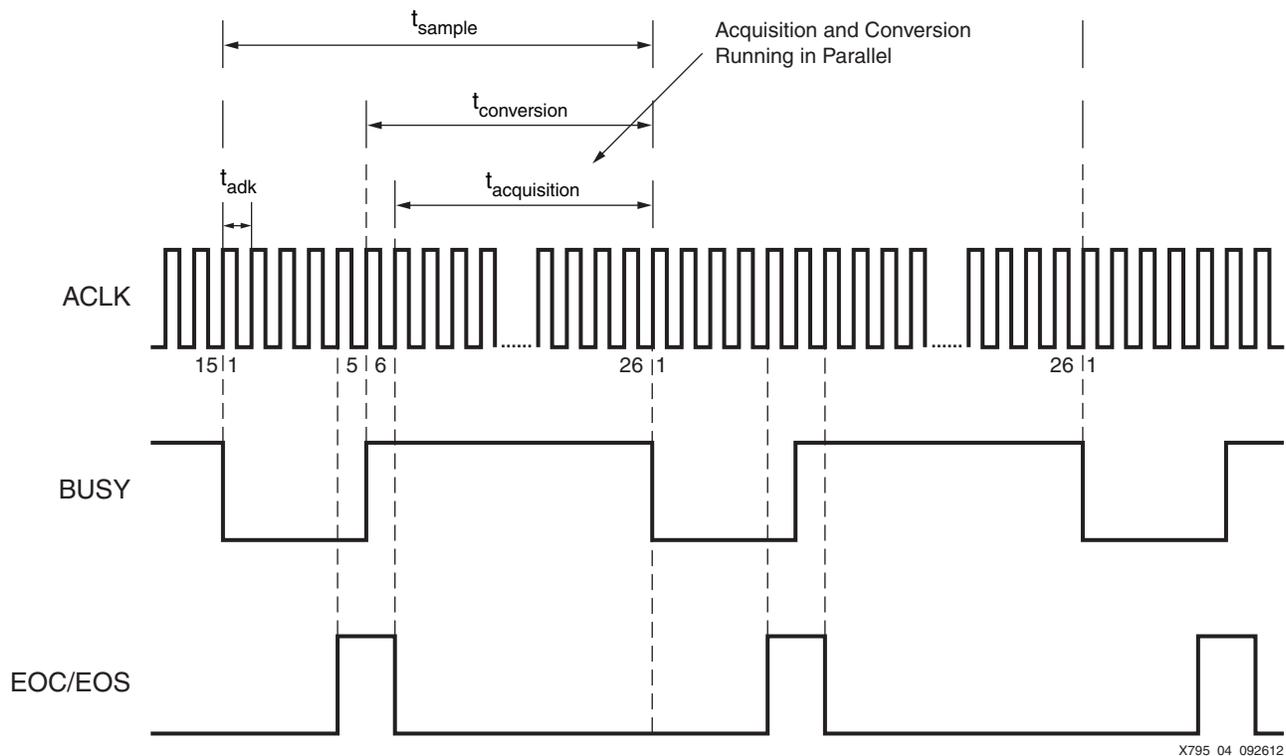


Figure 4: Acquisition and Conversion Timing Diagram

## Anti-Aliasing Filter Requirements

As with all ADCs, it is recommended that an anti-aliasing filter (AAF) be used and that it be placed as close to the inputs to the XADC as possible. This AAF stops unwanted high-frequency components of the signal from aliasing back into the bandwidth of interest due to the nature of the sampling process and impacting the performance of the XADC (see *What the Nyquist Criterion Means to Your Sampled Data System Design* [Ref 6]).

Ideally, the maximum cut-off frequency of the AAF should be the Nyquist rate of the converter. For an XADC running at 1 MSPS, the Nyquist frequency is 500 KHz when a single channel is being converted. The Nyquist frequency reduces linearly with the number of channels that are multiplexed into the 1 MSPS ADC. In general, it is not possible to have an AAF with a cut-off at the Nyquist frequency due to its impact on the settling time of the circuit. This issue is covered in subsequent sections of this application note.

The AAF is typically a simple passive filter made from resistors and capacitors. Figure 5 shows an AAF in front of the XADC. In each of the use cases that are presented, some guidelines are given in relation to the size of the resistors and capacitors for the AAF.

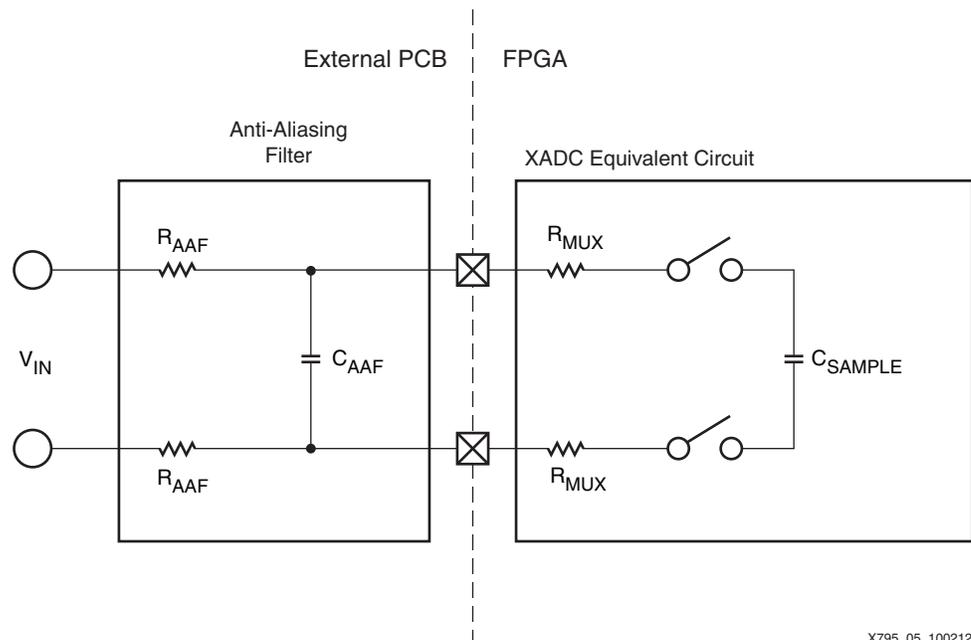


Figure 5: Anti-aliasing Filter Example Circuit

Given that the AAF adds more capacitance to the circuit, it can complicate the design somewhat. It is, however, a necessary evil because without an AAF, high-frequency noise or interference on the analog inputs can alias back into the bandwidth of interest during the sampling process and thus create significant performance loss.

## XADC Use Case Examples

As with the FPGA itself, the XADC tends to have a large number of potential use cases owing to the programmability of the device. This application note focuses on four of the most popular use cases:

- [Use Case 1: Voltage Monitoring](#)
- [Use Case 2: Measuring a Current](#)
- [Use Case 3: Measuring the Output from a Sensor](#)
- [Use Case 4: External Multiplexer Mode](#)

The analysis carried out for each of these use cases can be leveraged into design solutions for the various other use cases to which the XADC might lend itself.

### Use Case 1: Voltage Monitoring

One of the most popular use cases for the XADC is monitoring various voltages from around the board. These voltages typically include supply voltages and other reference voltages that can exceed the input range of the XADC. A simple solution to this problem is to use a resistor divider. This resistor divider delivers a voltage to the XADC that is some constant factor smaller than the voltage being measured. Figure 6 shows a simple resistor divider network.

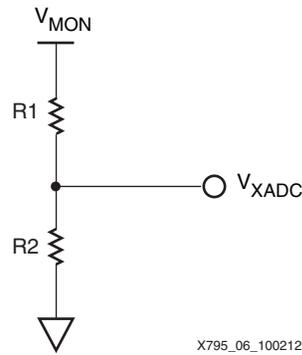


Figure 6: **Resistor Divider Circuit**

Equation 4 defines the  $V_{XADC}$  for the circuit shown in Figure 6.

$$V_{XADC} = V_{MON} \frac{R2}{R1 + R2} \quad \text{Equation 4}$$

Consider the case where  $V_{MON}$  is 5V and the desired  $V_{XADC}$  is 0.5V. This places  $V_{XADC}$  in the middle of the XADC range and thus allows sampling  $V_{MON}$  voltages of up to 10V and down to 0V, as shown in Equation 5.

$$\frac{V_{XADC}}{V_{MON}} = \frac{0.5}{5} = 0.10 = \frac{R2}{R1 + R2} \quad \text{Equation 5}$$

Or  $R1 = 9R2$ . Thus, if  $R2 = 1 \text{ k}\Omega$ ,  $R1 = 9 \text{ k}\Omega$ .

Ideally, the resistor values should be kept as low as possible to ensure that leakage current effects have minimal impact. The power consumption of the resistor divider network ultimately decides how low a resistance is tolerable.

The impact of this resistor divider on the settling time of the overall circuit including the AAF is shown in Figure 7. The settling time of the XADC equivalent circuit can be ignored because it is quick enough by itself (see Equation 3, page 3), and the AAF capacitor is many times larger than the  $C_{SAMPLE}$  value.

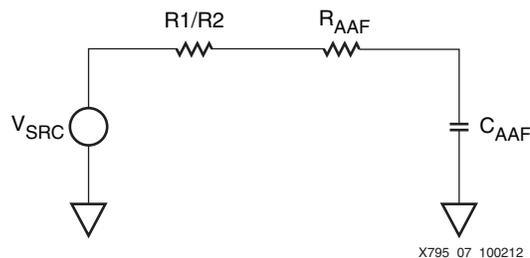


Figure 7: **Resistor Divider Circuit**

$R1|R2$  is the parallel combination of  $R1$  and  $R2$  where  $R1$  is  $1 \text{ k}\Omega$  and  $R2$  is  $9 \text{ k}\Omega$ . This equates to  $900\Omega$ , which is typically much larger than  $R_{AAF}$ , and thus  $R_{AAF}$  can be ignored.

For monitoring various voltages around the board, typically sampling them at a  $10 \mu\text{s}$  ( $100 \text{ Ks/s}$ ) sample rate is sufficient. To ensure a settling time of one half of a 12 bit LSB,  $C_{AAF}$  must be sized using Equation 6.

$$t_{\text{settle}} = 10\mu\text{s} = 9.01 \times R1|R2 \times C_{AAF} \quad \text{Equation 6}$$

This implies that  $C_{AAF}$  can be sized as shown in Equation 7.

$$C_{AAF} = \frac{10\mu s}{9.01 \times R1 | R2} = \frac{10\mu s}{9.01 \times 900} \sim 1.1 nF \quad \text{Equation 7}$$

The cutoff frequency for this RC circuit is 160 kHz, which is considerably larger than the Nyquist frequency (50 KHz) for an ADC running at 100 Ks/s. This is because a filter with a cutoff frequency of 50 KHz does not settle to 12 bits of accuracy in 10  $\mu$ s.

In many cases, the accuracy requirement is less than 10 bits. Thus, the settling time requirements can be reduced by replacing the 9.01 in Equation 7 with the appropriate number from Table 1, page 3.

Figure 8 shows a schematic with a resistor divider network being interfaced to the XADC input equivalent circuit with the passive components sized as calculated with Equation 6 and Equation 7.

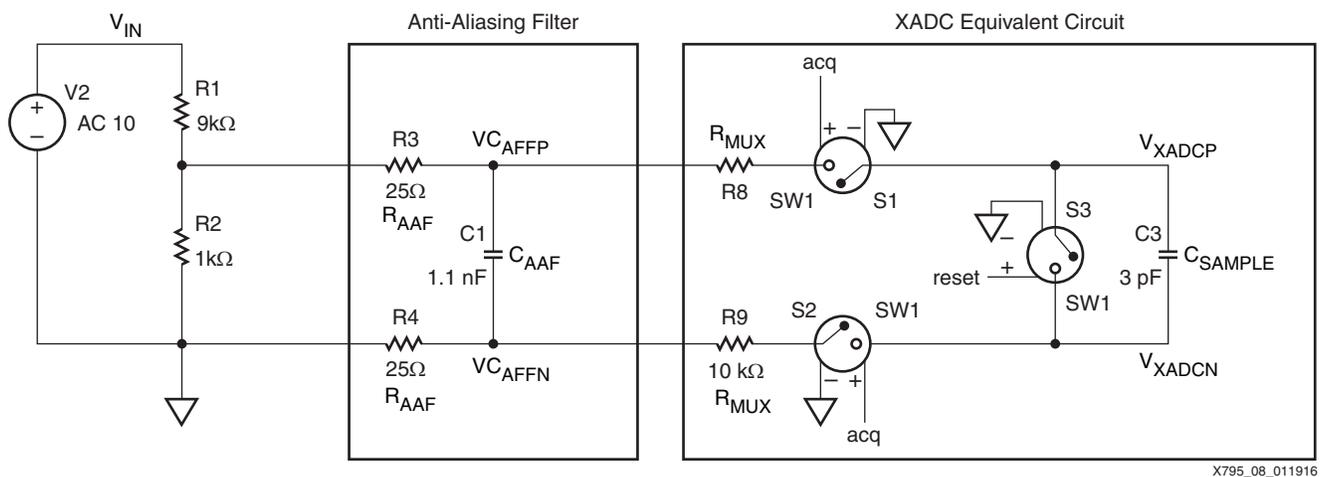


Figure 8: Resistor Divider Interfaced to XADC Simulation Circuit

Notes related to Figure 8:

1. Switches S1 and S2 should be closed during the period of the conversion labeled  $t_{\text{acquisition}}$  in Figure 4, page 4.
2. During the ADC conversion process, the  $C_{\text{SAMPLE}}$  capacitor gets reset. In any settling time simulation,  $C_{\text{SAMPLE}}$  should be reset before the acquisition time begins.

Figure 9 shows a simulation result showing that the circuit in Figure 8 settles to within 12 bits of accuracy in 9.725  $\mu\text{s}$ . The settling time requirement reduces to 8  $\mu\text{s}$  if only 10 bits of accuracy is needed.

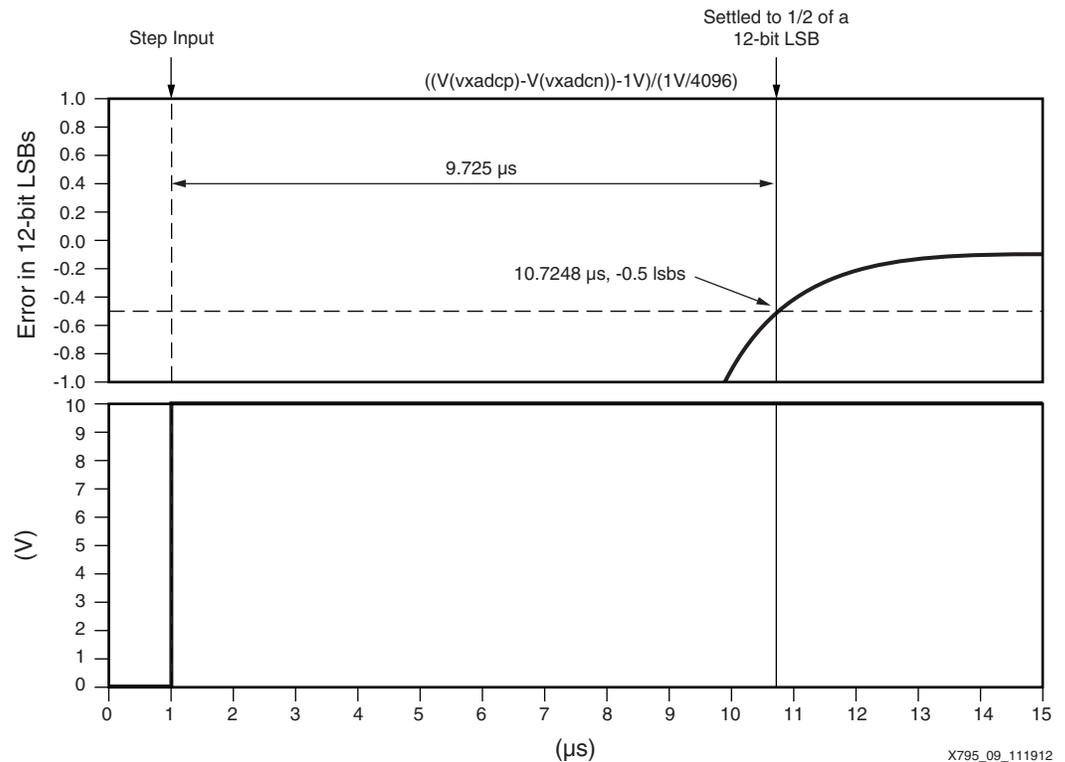


Figure 9: Simulation of Use Case 1 Showing Settling Time

A resistor divider circuit is shown in the Voltage Attenuation figure in 7 *Series FPGAs XADC Dual 12-Bit 1MSPS Analog-to-Digital Converter User Guide* [Ref 7]. In this circuit, a 4 k $\Omega$  resistor is placed in series with the resistor in the AAF on the N input side. The resistor is sized to equal the parallel combination of the two resistors that make up the resistor divider network. This resistor ensures that the impedance is balanced on both the P and N inputs to the XADC, helping to maximize the interference immunity of the circuit. This approach should be adopted when building a resistor divider circuit to drive the XADC. With this approach, the impact to the settling time of the circuit essentially doubles the size of the resistor in the RC circuit. Thus, to obtain the same settling times, the  $C_{AAF}$  capacitor value must be reduced by a factor of 2 to 0.55 nF.

## Use Case 2: Measuring a Current

Many ADC applications require measuring a current. The objective might be to measure the supply current or even the phase current of a motor. Typically, to measure a current flowing in a net, a resistor is placed directly in the current path, and the voltage drop across the resistor is measured. To ensure that there is not a significant voltage drop across the resistor, a value is selected that is a fraction of the total resistance of the load. A difference amplifier or instrumentation amplifier (in-amp) can be used to increase the gain of the voltage drop across the resistor to a level adequate for conversion by the ADC. These amplifier types can either be built up using discrete components or can come as a fully integrated solution. The most versatile and forgiving option is to use a fully integrated instrumentation amplifier, although this incurs an added cost. Tutorials are available that assist in choosing the best amplifier solution for a given situation (see *Difference and Current Sense Amplifiers* [Ref 8] and *Instrumentation Amplifier (In-Amp) Basics* [Ref 9]). Figure 10 shows a block diagram for such a current measurement circuit using an integrated differencing amplifier with built-in gain.

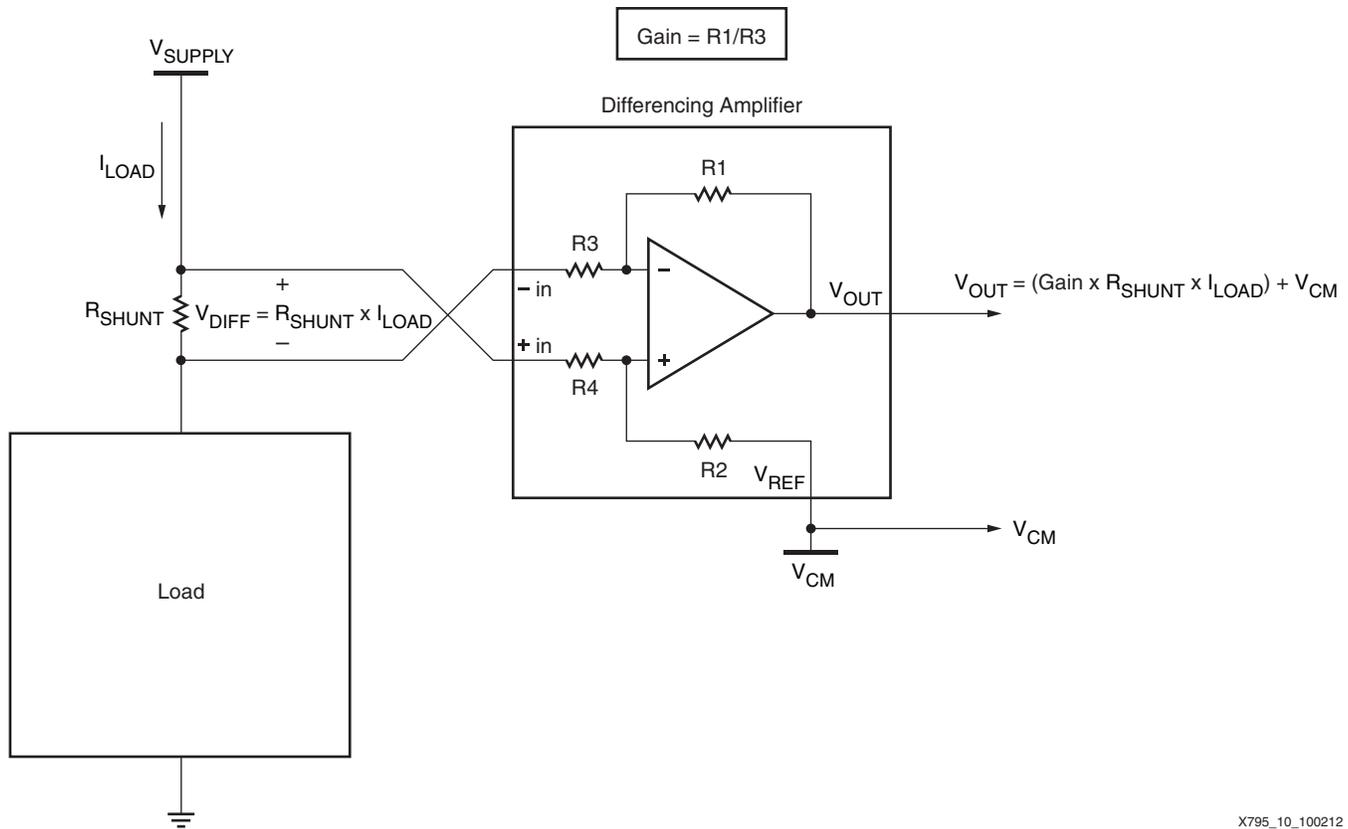


Figure 10: Current Measuring Circuit Using Integrated Difference Amplifier

Ideally, the solution shown in Figure 10 can be interfaced directly to an ADC. Certain ADCs might require a buffer or driving amplifier to be placed into the signal chain before the ADC. The XADC in general does not require a buffer amplifier. However, in certain applications the amplifier might be necessary to achieve the highest level of performance.

### Driving the XADC with a Standard In-Amp

Typically, standard in-amps are slow with an input bandwidth in the 10 to 100 KHz range. This can affect the ability of the amplifier to capture fast changes in current but, in most cases, this is not an issue. The in-amp must also be fast enough to recharge the input sample capacitance presented during the ADC acquisition phase.

Because of the mismatch between the XADC sample rate of 1 MSPS and the bandwidth of the amplifier, the XADC should be slowed to give the amplifier adequate time to settle the sample capacitor. In most applications, however, slowing the XADC is not necessary given that the in-amp has a very narrow input bandwidth. For higher performance applications, running the XADC at 1 MSPS is required to allow the XADC result to be over sampled and decimated to meet the dynamic range requirements of the design. This topic is covered later in this section of the application note.

Before fully analyzing the circuit, another consideration is the need for some anti-aliasing filtering between the instrumentation or differencing amplifier and the XADC. Figure 11 shows an example circuit that includes the AAF. Typically, it is not necessary for this AAF to operate at the Nyquist frequency of the ADC as the majority of the noise exists at or above 1 MHz. Operating an anti-aliasing filter at the Nyquist frequency of the ADC taxes the system by reducing the response time of the in-amp. For this example, an AAF with a cutoff frequency of 500 KHz is used. This frequency does not adversely affect the settling time of the in-amp but does filter out unwanted signals appearing at the analog inputs such as high-frequency noise from the amplifier power supply.

Equation 8 is used to implement an AAF with a cut-off frequency of 500 KHz.

$$500\text{KHz} = \frac{1}{2\pi(2R_{AAF})C_{AAF}} \quad \text{Equation 8}$$

The capacitance should be chosen by referencing the maximum load capacitance on the in-amp datasheet. The Texas Instruments *INA210–INA214 Data Sheet* [Ref 10] specifies a maximum capacitance of 1 nF. Using this specification, a value for  $R_{AAF}$  can be calculated with Equation 9.

$$6283\text{k} = \frac{1}{R_{AAF}C_{AAF}} = \frac{1}{R_{AAF}1\text{nF}} \quad \text{Equation 9}$$

$$R_{AAF} \cong 150\Omega$$

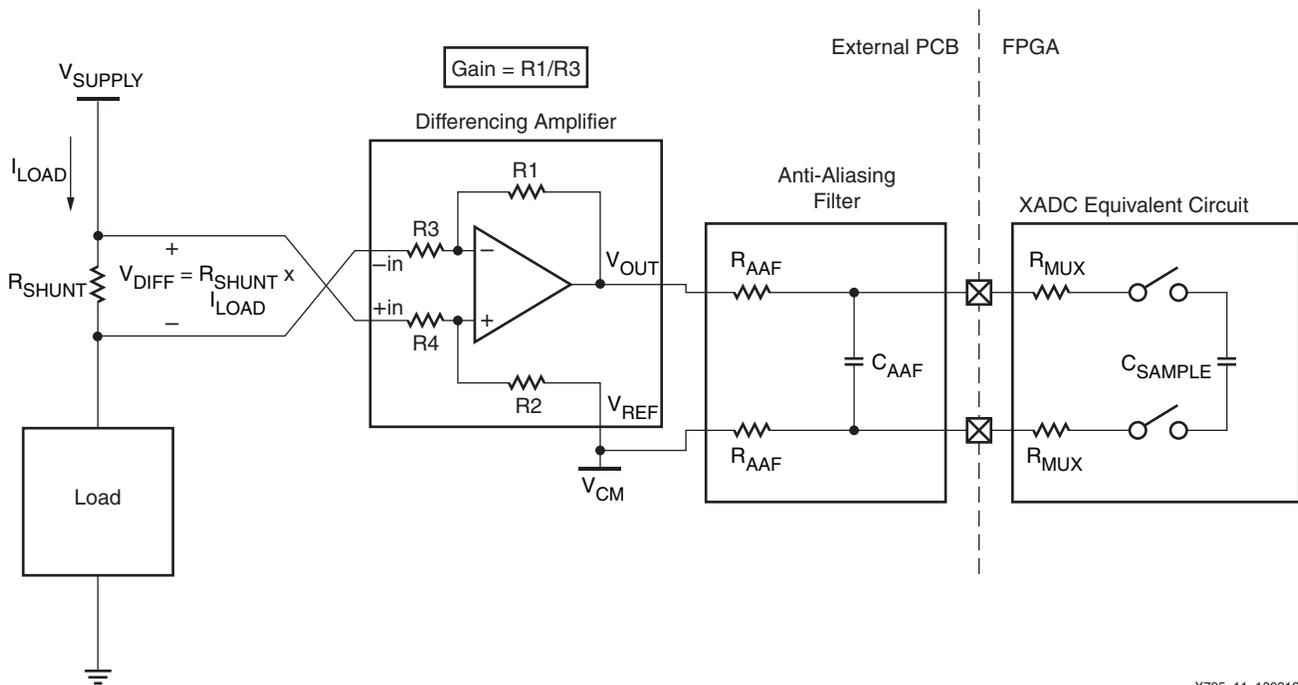


Figure 11: Direct Digitization of Difference Amplifier Output by the XADC

The next step is to determine the XADC sample rate at which the circuit settles to the required level of accuracy. This is determined by the maximum settling speed for the in-amp in question. Typically, the in-amp vendor quotes an input bandwidth specification that can be used to calculate the settling time of the circuit. However, this settling time often does not include a transient load effect response such as that caused by a switched capacitor circuit. The input response and the load response are of the same order with the load transient settling time being quicker. In this case, it is best to use the input bandwidth specification itself to calculate the settling time.

Another method is to just measure the response time, but this can be time consuming. Yet another approach is to use the SPICE models provided by the vendor, bearing in mind that these models might not deal with a load transient effect correctly resulting in a grossly underestimated settling time.

Equation 10 determines the sample rate of the XADC for a given amplifier bandwidth.

$$\text{XADC Sample Rate} = \frac{2\pi(\text{inamp}_{bw})}{\tau} \quad \text{Equation 10}$$

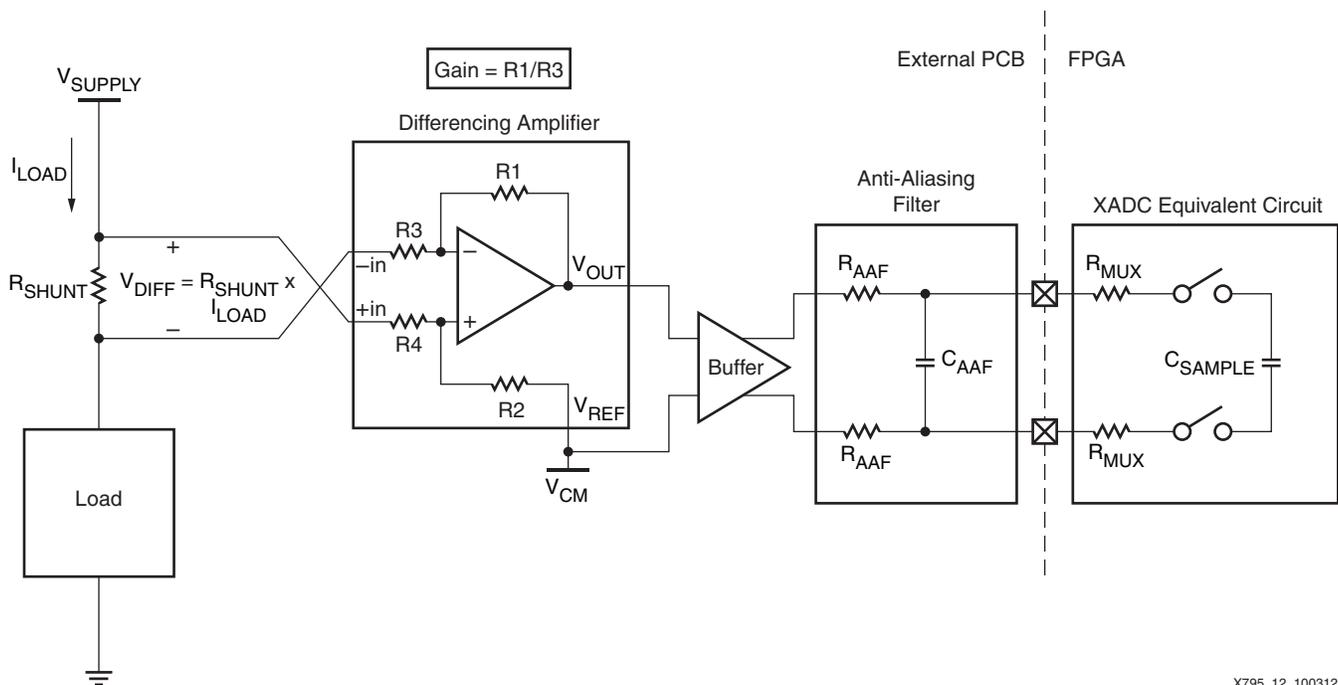
For 12 bits of accuracy using the INA213 differencing amplifier (Texas Instruments *INA210–INA214 Data Sheet* [Ref 10] Figure 7), the XADC sample rate is given by Equation 11.

$$XADC\text{SampleRate} = \frac{2\pi(100\text{kHz})}{9.01} \cong 70\text{KSPS} \quad \text{Equation 11}$$

For applications requiring only 10 bits of accuracy, the XADC sample rate is given by Equation 12.

$$XADC\text{SampleRate} = \frac{2\pi(100\text{kHz})}{7.62} \cong 80\text{KSPS} \quad \text{Equation 12}$$

For higher performance applications, the XADC should be operated at 1 MSPS to allow the result to be oversampled and decimated to meet the dynamic range requirements of the design. In this instance, a buffer might be required. The cost trade-off must be evaluated between purchasing a high-performance in-amp and purchasing a lower performance in-amp with an additional buffer. The in-amp only drives the buffer amplifier and the buffer takes care of driving the switched capacitor load presented by the XADC, as shown in Figure 12.

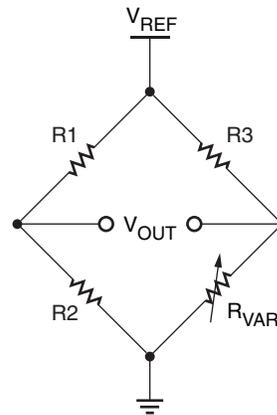


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Figure 12: Current Measurement Using a Buffer to Drive the XADC

### Use Case 3: Measuring the Output from a Sensor

Another very common use case for the XADC is measuring the output from a sensor. Typical applications include a strain gauge or temperature sensor such as a resistance temperature detector (RTD). For both a strain gauge and an RTD, the sensor resistance changes with the parameter measured. A typical method of measuring this change in resistance is to build a Wheatstone bridge circuit, as shown in figure Figure 13, where three of the resistors in the bridge have fixed values and the variable-resistance sensor forms the fourth resistor. The voltage between the two mid-points of the bridge varies proportionally to the change in resistance of the sensor, thus becoming a measure of the parameter in question.



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Figure 13: **Wheatstone Bridge Circuit for Measuring Change in Sensor Resistance**

The Wheatstone bridge feeds an ADC to digitize the voltage  $V_{OUT}$ . The bridge can interface directly to an instrumentation amplifier. A differencing amplifier is not used due to the loading effect caused by the series resistance it presents to the bridge. With this configuration, the circuit and analysis is the same as that in use case 2.

Sensor measurement requires a high degree of accuracy. Thus, the XADC should run as fast as possible to oversample or decimate its output to maximize the dynamic range. If the in-amp used does not have enough bandwidth to drive the XADC at these speeds, a buffer amplifier is required, similar to that shown in [Figure 12](#).

#### Use Case 4: External Multiplexer Mode

Given the many uses for the XADC, it is common to have a shortage of spare I/O ports to connect all of the required external analog signals to the XADC. An easy solution to this problem is adding an external multiplexer (MUX) to the design. The external MUX reduces the number of required pins on the FPGA while allowing a large number of analog signals to be connected and digitized by the XADC. A block diagram of this solution is shown in [Figure 14](#). The XADC also has some built-in features that allow this use case without additional FPGA coding. See the External Multiplexer Mode section of *7 Series FPGAs XADC Dual 12-Bit 1MSPS Analog-to-Digital Converter User Guide* [[Ref 7](#)] for more details on these features.

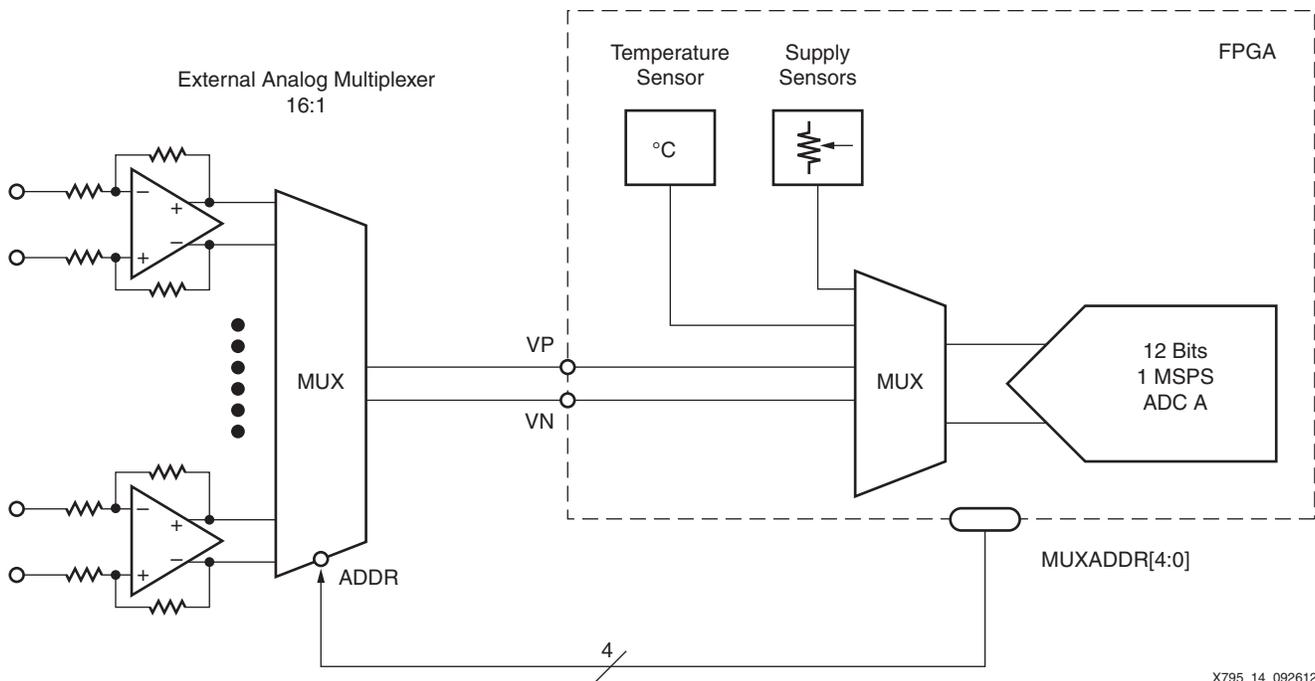


Figure 14: External Multiplexer Mode

Designing circuits that settle in time is a little more challenging and potentially less forgiving when using an external MUX. In prior cases, only the sample capacitor of the XADC needed to be recharged on every XADC sample. In the case of the external multiplexer, any external capacitance on the output side of the multiplexer must be completely charged to the desired voltage. This includes any board capacitance between the output of the MUX and the sample capacitor of the ADC, as well as any capacitance that makes up an AAF between the MUX output and the XADC input. The board capacitance alone is on the order of 10 pF and the AAF capacitor is much larger. In addition to the capacitance issue, settling errors in a multiplexed application can result in crosstalk from the previous channel selected by the multiplexer to the current channel. See *Understanding Crosstalk in Analog Multiplexers* [Ref 11].

Given the large number of analog input channels that are needed in such applications, slowing the XADC presents a problem as the bandwidth per channel quickly becomes too small. The XADC is run at the full 1 MSPS rate to provide each channel enough bandwidth. This means each channel that is connected to the multiplexer must be capable of driving the capacitance at the output of the multiplexer in less than 1  $\mu$ s. This capability generally requires an operational amplifier.

Adding an operational amplifier to each pin can be expensive. An alternate solution is to place a single buffer directly at the output of the MUX. The buffer should be positioned as close as possible to the output side of the MUX to minimize the buffer input capacitance. Each channel must only drive the input of the amplifier within 1  $\mu$ s. An anti-aliasing filter can be placed at the buffer output prior to the XADC to remove extraneous high-frequency signals. This AAF should be designed to settle within the allowed acquisition time of the XADC. Figure 15 shows a block diagram of a buffered external multiplexer.

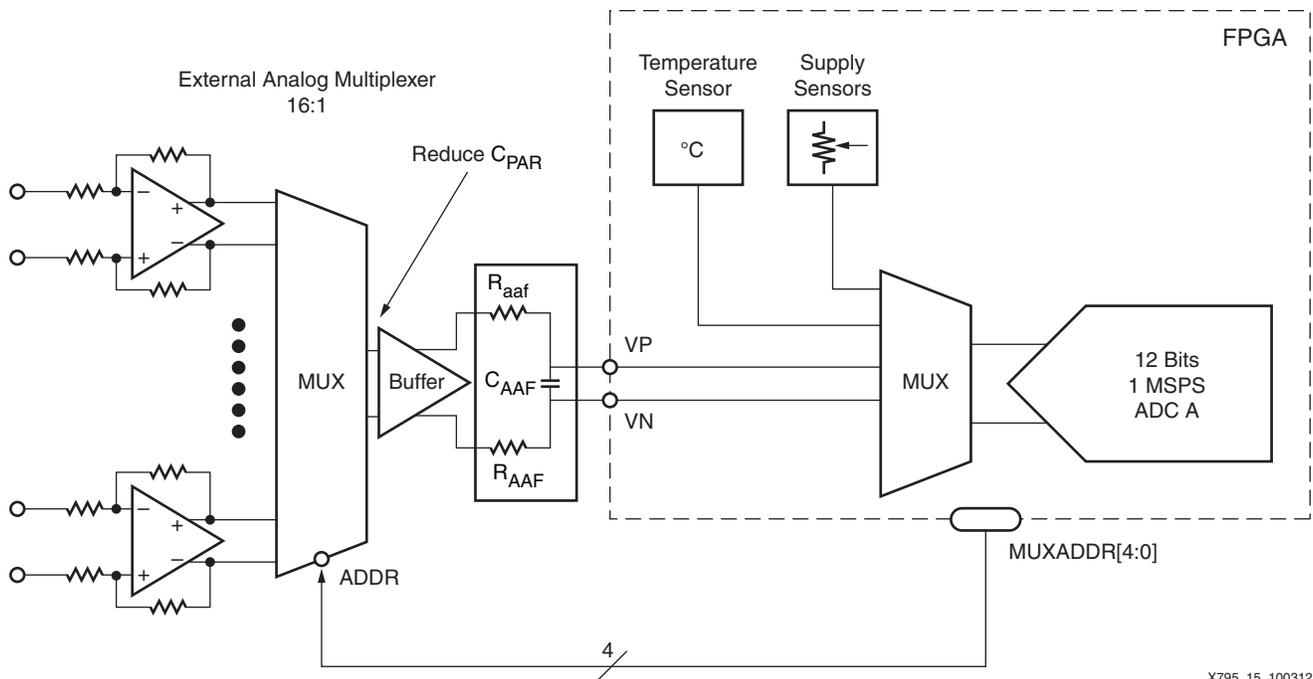


Figure 15: External Multiplexer Use Case with Buffer at Multiplexer Output

Given that the maximum linear settling time of the XADC input circuitry is 540 ns, the resistors and capacitors making up the AAF should be sized for a time constant of 9.01, which equates to approximately 500 ns. A settling time requirement of 500 ns ensures that the XADC and AAF settle within 75% (750 ns) of the sampling period (1  $\mu$ s). This requires the AAF and the XADC sampling network to both settle in 750 ns. Thus, Equation 13 to Equation 15 must be true.

$$t_{settle_{overall}} = \sqrt{(t_{settle_{AAF}})^2 + (t_{settle_{XADC_{input}}})^2} \quad \text{Equation 13}$$

$$(t_{settle_{AAF}})^2 = (750ns)^2 - (540ns)^2 \quad \text{Equation 14}$$

$$t_{settle_{AAF}} \sim 500ns \quad \text{Equation 15}$$

Assuming the AAF circuit shown in Figure 5, page 5, the AAF resistors and capacitors should be sized according to Equation 16.

$$2R_{AAF}C_{AAF} = \frac{500ns}{9.01} = 55ns \quad \text{Equation 16}$$

Assuming  $C_{AAF}$  is 1 nF,  $R_{AAF}$  is approximately 25 $\Omega$ .

Each input to the MUX must now be capable of driving the parasitic capacitance and the output of the MUX but not the AAF, the parasitic board capacitance, or the XADC input. If the board is carefully laid out, the capacitance can be limited to less than 5 pF, including the input capacitance of the buffer.

### Resistor Divider External MUX Input

For a resistor divider circuit as shown in Figure 6, page 6, the maximum parallel combination of R1 and R2 is given in Equation 17.

$$R1|R2 = \frac{t_{settle}}{\tau C_{PAR}} = \frac{500ns}{9.01(5p)} = 55k\Omega \quad \text{Equation 17}$$

The parallel combination of R1|R2 is typically less than 1 k $\Omega$  because of leakage concerns. Thus, keeping the resistance below 55 k $\Omega$  is not an issue, and there are no settling time concerns for the circuit.

### In-amp External MUX Input

Some instrumentation amplifiers are too slow to drive the 5 pF of parasitic capacitance at the output of the external MUX. When using an external MUX, there are likely to be a large number of channels. Slowing the XADC to accommodate one slow channel driven by an in-amp requires all other channels to slow down as well when operating in automatic sequencer mode.

Because of this, it is recommended to follow each in-amp with a buffer prior to it being interfaced to the MUX. This buffer can easily drive the parasitic capacitance at the output of the MUX in much less than 500 ns.

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## Conclusion

This application note illustrates the care that must be taken when driving ADCs with switched capacitor inputs. The XADC has a switched capacitor input but it also has some unique benefits that extend the acquisition time of the XADC when compared to other discrete ADCs.

This application note presents example solutions to driving the XADC in a number of common use cases. By following the simple guidelines presented, most analog interface requirements are easily accommodated.

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## References

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## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
12/12/12	1.0	Initial Xilinx release.
02/24/16	1.1	Removed R5 resistor from <a href="#">Figure 8</a> .

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